



# **MXD8921H**

**SiGe Low Noise Amplifier**

**with Bypass Mode for LTE Mid-High Band**

**Rev1.3**

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## General Description

MXD8921H high gain, low noise amplifier (LNA) is dedicated to LTE middle band and high band receive using advanced SiGe process. This product has two operation modes, low noise mode and bypass mode.

MXD8921H works under a 1.6V to 3.6V single power supply while consumes 4.2 mA current in low noise mode, in bypass mode, the power consumption will be reduced to less than 1uA.

MXD8921H uses a small 1.1mm × 0.7mm × 0.45mm LGA 6-pin package.

## Applications

- LTE high-mid band receiving

## Features

- Broadband frequency range: 1.7G to 2.7 GHz
- High Gain
  - 14.6dB gain at 1.7GHz to 1.8GHz
  - 14.5dB gain at 1.8GHz to 2.2GHz
  - 13.5dB gain at 2.3GHz to 2.7GHz
- Ultra low noise figure
  - 0.60dB noise figure at 1.7GHz to 1.8GHz
  - 0.65dB noise figure at 1.8GHz to 2.2GHz
  - 0.8dB noise figure at 2.3GHz to 2.7GHz
- Operation current 4.2mA
- Single supply voltage range 1.6V to 3.6V
- Small, LGA (6-pin, 1.1mm x 0.7mm x 0.45mm) package , MSL1

## Pin Configuration/Application Diagram (Top view)

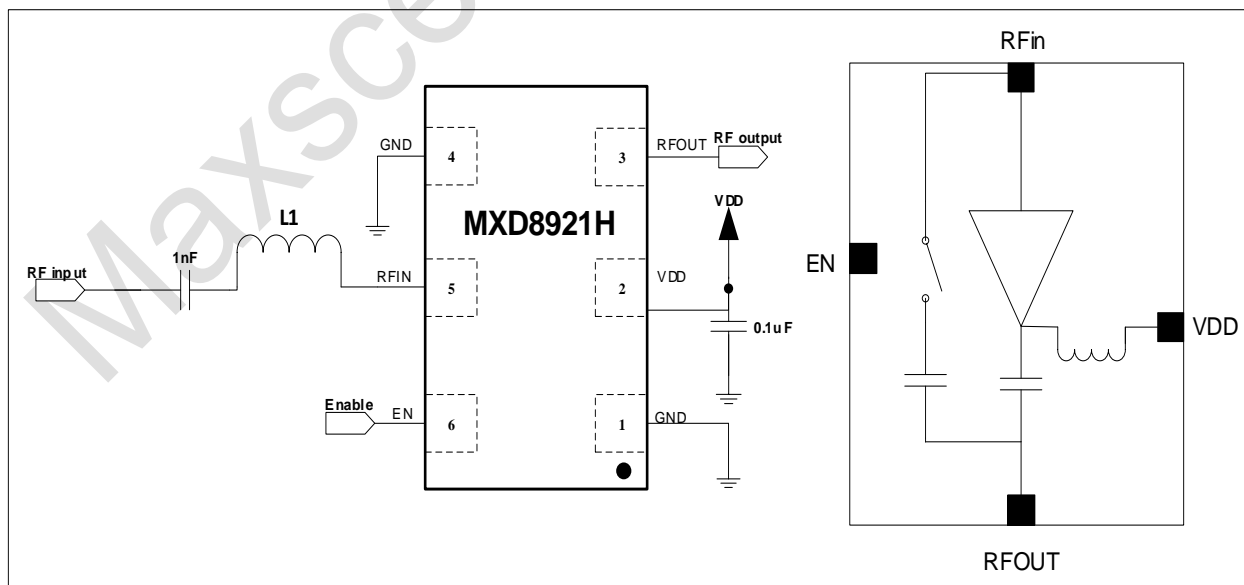


Figure 1 MXD8921H application circuit

## Pin Descriptions & Input matching inductance

**Table 1**

Pin	Pin Name	I/O	Pin Description
1	GND	AG	Analog VSS
2	VDD	AP	Power supply
3	RFOUT	AO	LNA output
4	GND	AG	Analog VSS
5	RFIN	AI	LNA input from antenna
6	EN	DI	Pull high into low noise mode, pull low into bypass mode

**Note:** DI (digital input), DO (digital output), DIO (digital bidirectional), AI (analog input), AO (analog output), AIO (analog bidirectional), AP (analog power), AG (analog ground),

**Table 2 Input matching inductance**

Component	Matching Band	Vendor	Type	Part Number & value
L1	1700MHz – 1800MHz	Murata	Wired inductor, high Q	LQW15AN, 5.1nH
		various	Ceramic inductor, low Q	4.7nH
	1800MHz – 2200MHz	Murata	Wired inductor, high Q	LQW15AN, 4.6nH
		various	Ceramic inductor, low Q	4nH
	2300MHz – 2700MHz	Murata	Wired inductor, high Q	LQW15AN, 3.9nH
		various	Ceramic inductor, low Q	3.3nH

## Recommended Operation Range

**Table 3**

Parameters	Symbol	Min	Typ	Max	Units
Operation Frequency	f1	1700	-	2700	MHz
Power supply	V <sub>DD</sub>	1.6	2.8	3.6	V
Control Voltage High	V <sub>CTL_H</sub>	1.0	1.8	VDD	V
Control Voltage Low	V <sub>CTL_L</sub>	0	0	0.3	V

## Absolute Maximum Ratings

**Table 4 Maximum ratings**

Parameters	Symbol	Minimum	Maximum	Units
Supply voltage	V <sub>DD</sub>	-0.3	+4.0	V
Digital control voltage	V <sub>CTL</sub>	-0.3	VDD+0.3	V
RF input power	P <sub>IN</sub>	-	+25	dBm
Operating temperature	T <sub>OP</sub>	-40	+90	°C
Storage temperature	T <sub>STG</sub>	-65	+160	°C
Electrostatic Discharge Human body model (HBM), Class 1B <sup>Note1</sup>	ESD_HBM	-	2000	V
Charged device model (CDM), Class III <sup>Note2</sup>	ESD_CDM	-	1000	V

**Note:** Exposure to maximum rating conditions for extended periods may reduce device reliability. There is no damage to device with only one parameter set at the limit and all other parameters set at or below their nominal value. Exceeding any of the limits listed here may result in permanent damage to the device.

**Note1:** According to ESDA/JEDECJS-001-2014

**Note2:** According to ESDA/JEDECJS-002-2014

**Specifications**

 Typically  $T_A=25^{\circ}\text{C}$   $V_{DD}=2.8\text{V}$ , All data measured on Maxscend's EVB, unless otherwise noted

**Table 5 High Gain mode Electrical Specifications**

Parameter	Symbol	Specification			Units	Test Condition
		Min.	Typical	Max.		
<b>DC Specifications</b>						
Supply voltage	$V_{DD}$	1.6	2.8	3.6	V	
Supply current	$I_{DD}$	3	4.2	5.8	mA	$V_{DD} = 2.8\text{V}$ , $V_{EN}=1.8\text{V}$
<b>RF Specifications</b>						
Power gain	G	12.6	14.6	16.6	dB	1700-1800MHz
		12.5	14.5	16.5	dB	1800-2200MHz
		11.5	13.5	15.5	dB	2300-2700MHz
Noise figure	NF	-	0.6	0.95	dB	1700-1800MHz
		-	0.65	1.0	dB	1800-2200MHz
		-	0.8	1.15	dB	2300-2700MHz
Input Return loss	S11	-	-8	-4	dB	1700-1800MHz
		-	-10	-5	dB	1800-2200MHz
		-	-12	-6	dB	2300-2700MHz
Output Return loss	S22	-	-8	-4	dB	1700-1800MHz
		-	-12	-6	dB	1800-2200MHz
		-	-14	-8	dB	2300-2700MHz
Isolation	ISL	-	-23	-18	dB	1700 to 2700MHz
Stability factor	Kf	1.0	-	-		
Input 1 dB compression point	P1dB	-8.3	-4.8	-	dBm	at 2GHz
		-6	-2.5	-	dBm	at 2.5GHz
Input IP3	IIP3	0	5	-	dBm	Note1
		2	7	-	dBm	Note2
Switch time	turn-on-time	-	-	4	$\mu\text{s}$	Bypass state to High gain state, to 90% of the Gain
	turn-off-time	-	-	1	$\mu\text{s}$	High Gain state to Bypass state, to 10% of the Gain

Note1: Pin=Pin2=-20dBm, F1=2000MHz, F2=2001MHz

Note2: Pin=Pin2=-20dBm, F1=2500MHz, F2=2501MHz

**Table 6 Bypass mode Electrical Specifications**

Parameter	Symbol	Specification			Units	Test Condition
		Min.	Typical	Max.		
<b>DC Specifications</b>						
Supply voltage	$V_{DD}$	1.6	2.8	3.6	V	
Supply current	$I_{DD}$	0	0.1	1	$\mu\text{A}$	$V_{DD} = 2.8\text{V}$ , $V_{EN}=\text{low}$
<b>RF Specifications</b>						
Insertion loss	IL	-8	-5	-	dB	1700-1800MHz
		-7	-4	-	dB	1800-2700MHz
Input Return loss	S11	-	-10	-5	dB	1700 to 2700MHz
Output Return loss	S22	-	-10	-5	dB	1700 to 2700MHz
Input 1 dB compression point	P1dB	5	10	-	dBm	1700 to 2700MHz

**Specifications**

 Typically  $T_A=25^{\circ}\text{C}$   $V_{DD}=1.8\text{V}$ , All data measured on Maxscend's EVB, unless otherwise noted

**Table 7 High Gain mode Electrical Specifications**

Parameter	Symbol	Specification			Units	Test Condition
		Min.	Typical	Max.		
<b>DC Specifications</b>						
Supply voltage	$V_{DD}$	1.6	1.8	3.6	V	
Supply current	$I_{DD}$	2.8	4.0	5.6	mA	$V_{DD} = 1.8\text{V}$ , $V_{EN}=1.8\text{V}$
<b>RF Specifications</b>						
Power gain	G	12.3	14.3	16.3	dB	1700-1800MHz
		12.2	14.2	16.2	dB	1800-2200MHz
		11.2	13.2	15.2	dB	2300-2700MHz
Noise figure	NF	-	0.6	0.95	dB	1700-1800MHz
		-	0.65	1.0	dB	1800-2200MHz
		-	0.8	1.15	dB	2300-2700MHz
Input Return loss	S11	-	-8	-4	dB	1700-1800MHz
		-	-10	-5	dB	1800-2200MHz
		-	-12	-6	dB	2300-2700MHz
Output Return loss	S22	-	-8	-4	dB	1700-1800MHz
		-	-12	-6	dB	1800-2200MHz
		-	-14	-8	dB	2300-2700MHz
Isolation	ISL	-	-23	-18	dB	1700 to 2700MHz
Stability factor	Kf	1.0	-	-		
Input 1 dB compression point	P1dB	-10.5	-7	-	dBm	at 2GHz
		-8.5	-5	-	dBm	at 2.5GHz
Input IP3	IIP3	-1	3	-	dBm	Note1
		0	5	-	dBm	Note2
Switch time	turn-on-time	-	-	4	$\mu\text{s}$	Bypass state to High gain state, to 90% of the Gain
	turn-off-time	-	-	1	$\mu\text{s}$	High Gain state to Bypass state, to 10% of the Gain

Note1: Pin=Pin2=-20dBm, F1=2000MHz, F2=2001MHz

Note2: Pin=Pin2=-20dBm, F1=2500MHz, F2=2501MHz

**Table 8 Bypass mode Electrical Specifications**

Parameter	Symbol	Specification			Units	Test Condition
		Min.	Typical	Max.		
<b>DC Specifications</b>						
Supply voltage	$V_{DD}$	1.6	1.8	3.6	V	
Supply current	$I_{DD}$	0	0.1	1	$\mu\text{A}$	$V_{DD} = 1.8\text{V}$ , $V_{EN}=\text{low}$
<b>RF Specifications</b>						
Insertion loss	IL	-8.4	-5.4	-	dB	1700-1800MHz
		-7.4	-4.4	-	dB	1800-2700MHz
Input Return loss	S11	-	-10	-5	dB	1700 to 2700MHz
Output Return loss	S22	-	-10	-5	dB	1700 to 2700MHz
Input 1 dB compression point	P1dB	5	10	-	dBm	1700 to 2700MHz

Package Outline Dimensions

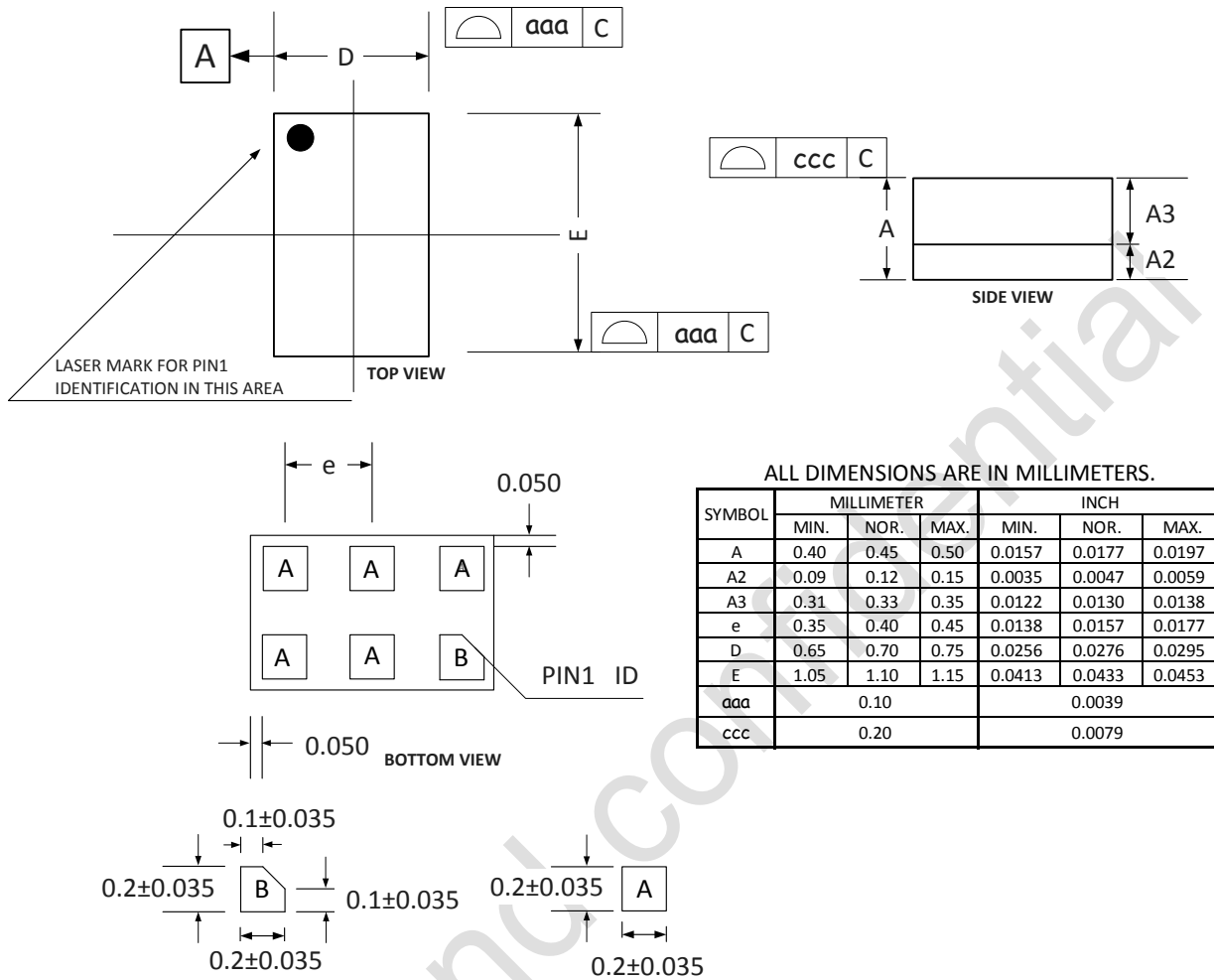


Figure 2 MXD8921H outline dimension

### Marking Specification

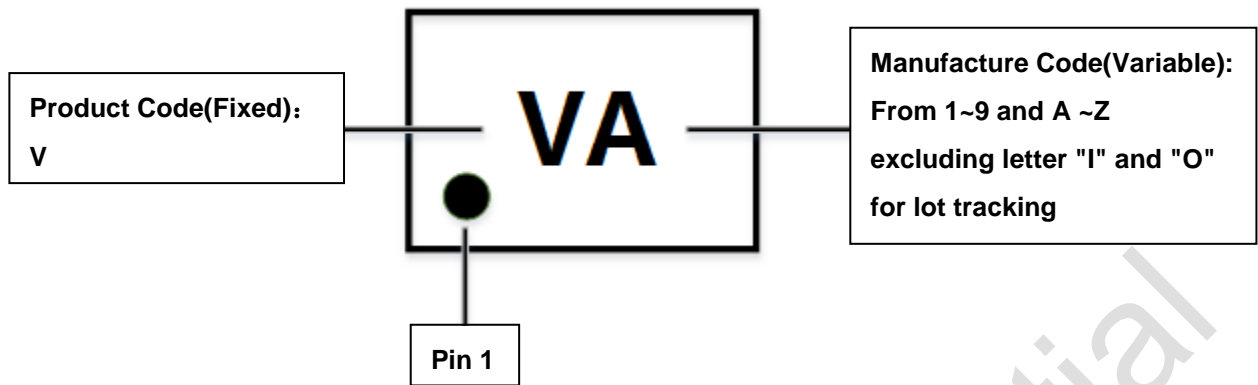


Figure 3 Marking specification (Top View)

### Tape and Reel Dimensions

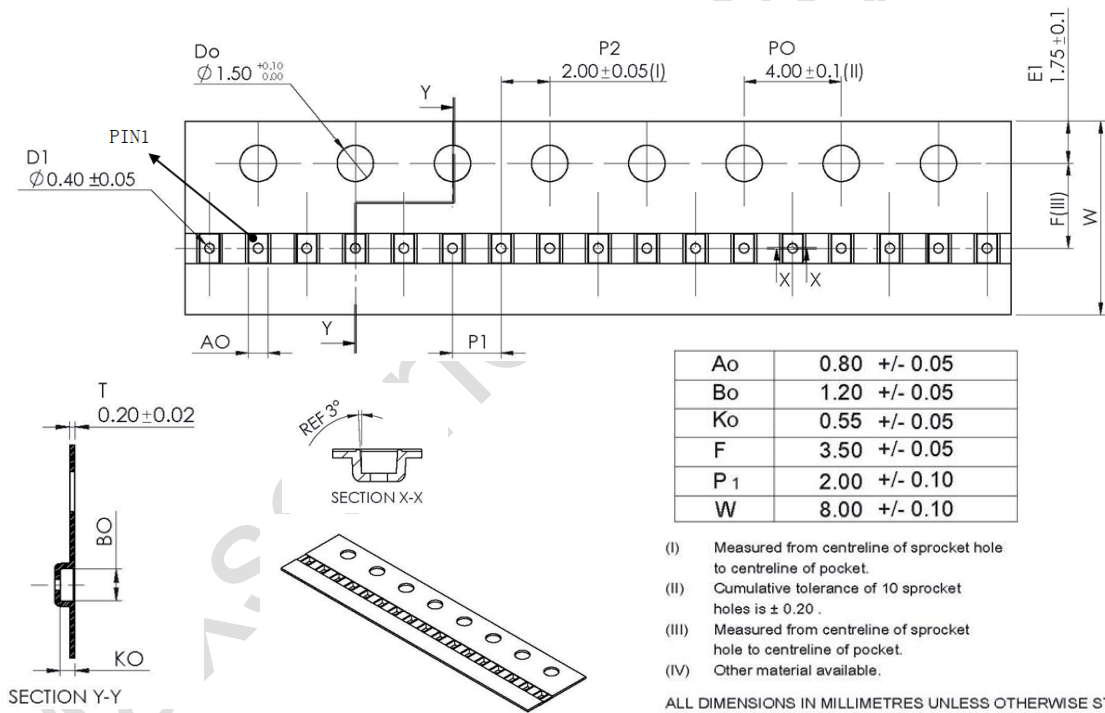


Figure 4 Tape and reel dimensions

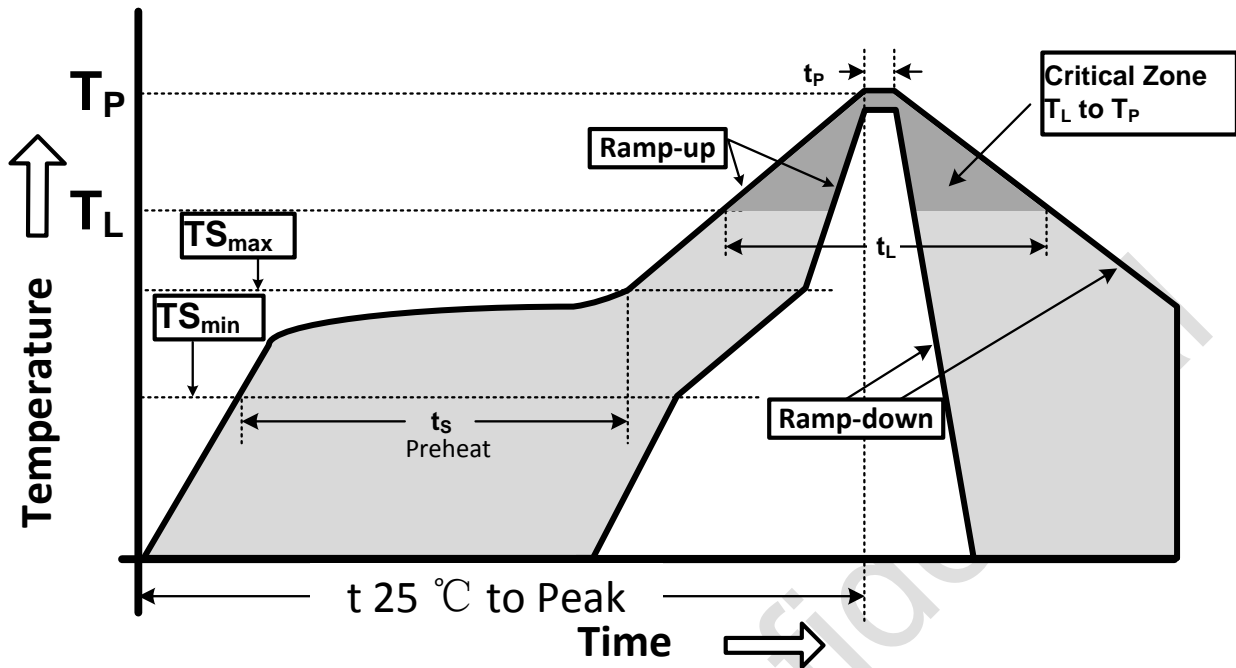
**Reflow Chart**


Figure 5 Recommended Lead-Free Reflow Profile

**Table 9 Reflow condition**

Profile Parameter	Lead-Free Assembly, Convection, IR/Convection
Ramp-up rate ( $T_{S_{max}}$ to $T_p$ )	3°C/second max.
Preheat temperature ( $T_{S_{min}}$ to $T_{S_{max}}$ )	150°C to 200°C
Preheat time ( $t_s$ )	60 - 180 seconds
Time above $T_L$ , 217°C ( $t_L$ )	60 - 150 seconds
Peak temperature ( $T_p$ )	260°C
Time within 5°C of peak temperature( $t_p$ )	20 - 40 seconds
Ramp-down rate	6°C/second max.
Time 25°C to peak temperature	8 minutes max.

**ESD Sensitivity**

Integrated circuits are ESD sensitive and can be damaged by static electric charge. Proper ESD protection techniques should be used when handling these devices.

**RoHS Compliant**

This product does not contain lead, mercury, cadmium, hexavalent chromium, polybrominated biphenyls (PBB) and polybrominated diphenyl ethers (PBDE), and are considered RoHS compliant.

1.3.1



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